

FQPF33N10L

100V LOGIC N-Channel MOSFET

General Description

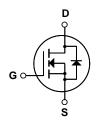
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as high efficiency switching DC/DC converters, and DC motor control.

Features

- 18A, 100V, $R_{DS(on)} = 0.052\Omega$ @V_{GS} = 10 V Low gate charge (typical 30 nC)
- Low Crss (typical 70 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQPF33N10L	Units	
V_{DSS}	Drain-Source Voltage		100	V	
I _D	Drain Current - Continuous (T _C = 25°C)		18	А	
	- Continuous (T _C = 100°C)		12.7	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	72	А	
V_{GSS}	Gate-Source Voltage		± 20	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	430	mJ	
I _{AR}	Avalanche Current	(Note 1)	18	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.1	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns	
P _D	Power Dissipation (T _C = 25°C)		41	W	
	- Derate above 25°C		0.27	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.7	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W	

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°	C	0.09		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 80 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V V _{GS} = -20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse				-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.0	V
R _{DS(on)}	Static Drain-Source	V _{GS} = 10 V, I _D = 9 A V _{GS} = 5 V, I _D = 9 A		0.039	0.052	Ω
103(011)	On-Resistance			0.043	0.055	
9 _{FS}	Forward Transconductance	$V_{DS} = 30 \text{ V}, I_{D} = 9 \text{ A}$ (Note	4)	22		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		1250 305 70	1630 400 90	pF pF
	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 50 V, I _D = 33 A,		17	45	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		470	950	ns
t _{d(off)}	Turn-Off Delay Time			70	150	ns
t _f	Turn-Off Fall Time	(Note 4	5)	120	250	ns
	Total Gate Charge	V _{DS} = 80 V, I _D = 33 A,		30	40	nC
\mathbf{q}_{g}		20 2		4.7		nC
	Gate-Source Charge	$V_{GS} = 5 V$				
Q _g Q _{gs} Q _{gd}	Gate-Source Charge Gate-Drain Charge	$V_{GS} = 5 \text{ V}$ (Note 4,		16		nC
Q _{gs} Q _{gd} Drain-S	Gate-Drain Charge	(Note 4,	5)			
Q _{gs} Q _{gd} Drain-S	Gate-Drain Charge Source Diode Characteristics and Maximum Continuous Drain-Source Dio	(Note 4,	5)		18	A
Q _{gs} Q _{gd} Drain-S I _S	Gate-Drain Charge Source Diode Characteristics at Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	nd Maximum Ratings ode Forward Current (Note 4)	6)		18 72	A
Q _{gs} Q _{gd}	Gate-Drain Charge Source Diode Characteristics and Maximum Continuous Drain-Source Dio	(Note 4,	5)		18	A

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 2.0mH, I_{AS} = 18A, V_{DD} = 25V, R_{G} = 25 Ω , Starting T_{J} = 25°C 3. I_{SD} ≤ 33A, di/dt ≤ 300A/ μ s, V_{DD} ≤ BV $_{DSS}$, Starting T_{J} = 25°C 4. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Typical Characteristics

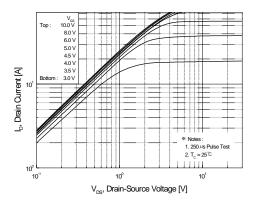


Figure 1. On-Region Characteristics

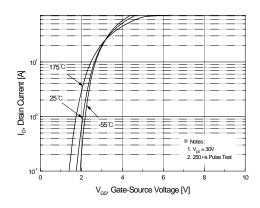


Figure 2. Transfer Characteristics

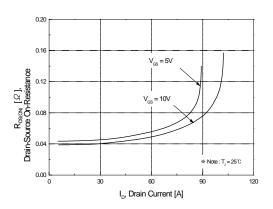


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

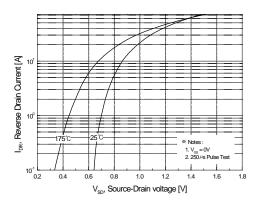


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

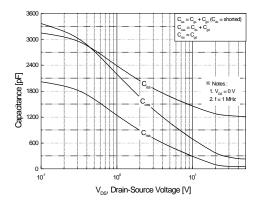


Figure 5. Capacitance Characteristics

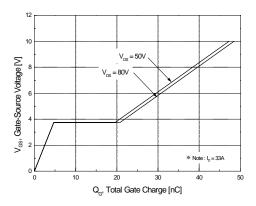
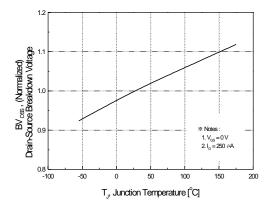


Figure 6. Gate Charge Characteristics

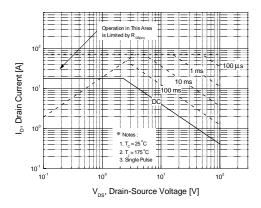
Typical Characteristics (Continued)



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Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



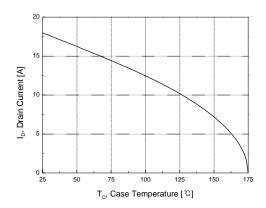


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

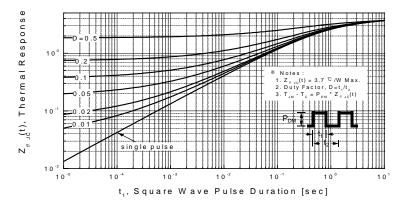
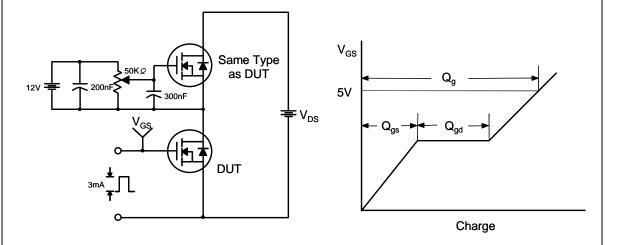


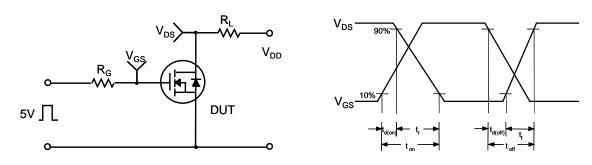
Figure 11. Transient Thermal Response Curve

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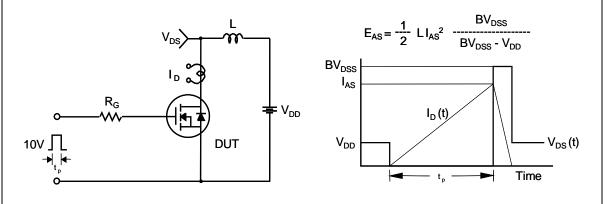
Gate Charge Test Circuit & Waveform



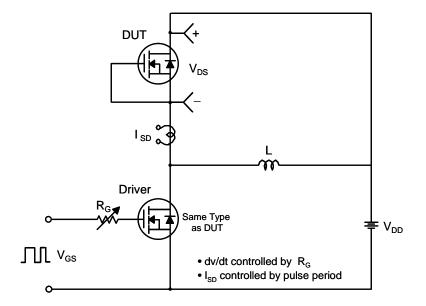
Resistive Switching Test Circuit & Waveforms

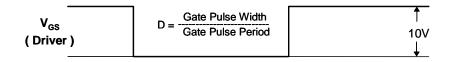


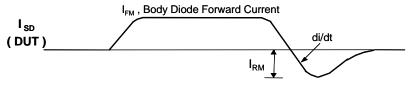
Unclamped Inductive Switching Test Circuit & Waveforms



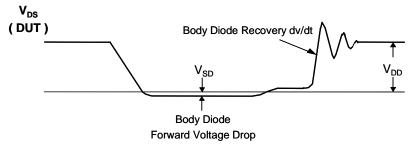
Peak Diode Recovery dv/dt Test Circuit & Waveforms

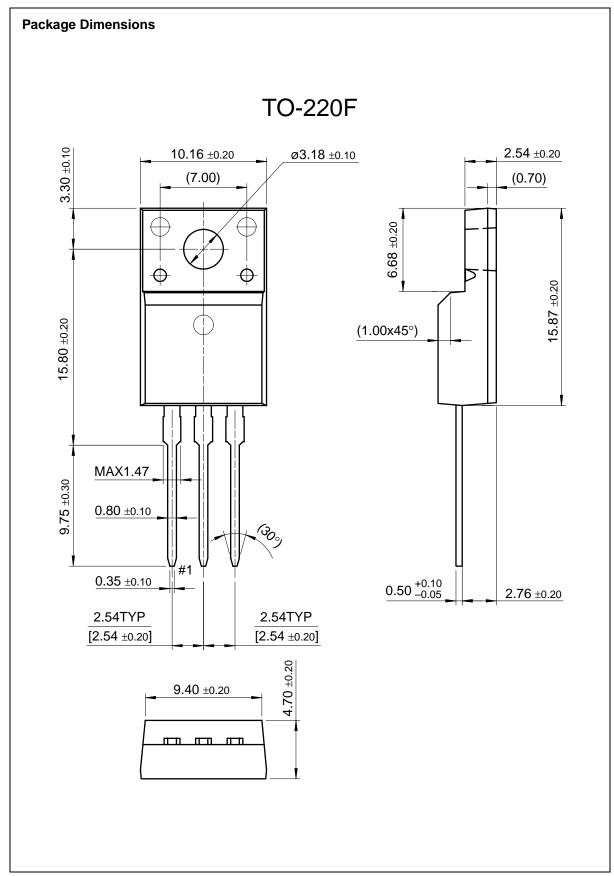






Body Diode Reverse Current





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